

Abstract

The present invention provides: a curable resin composition having a low dielectric loss tangent; and a cured product of the same. This curable resin composition contains: a compound represented by formula (1); and a compound having one ethylenically unsaturated double bond in the molecule. In formula (1), a plurality of R each independently represent a hydrogen atom, a hydrocarbon group having 1-10 carbon atoms, or a halogenated alkyl group having 1-10 carbon atoms. p and r each represent an integer of 0-4, q represents an integer of 0-3, and n represents the average of number of repeats and satisfies $1 \leq n \leq 20$.

